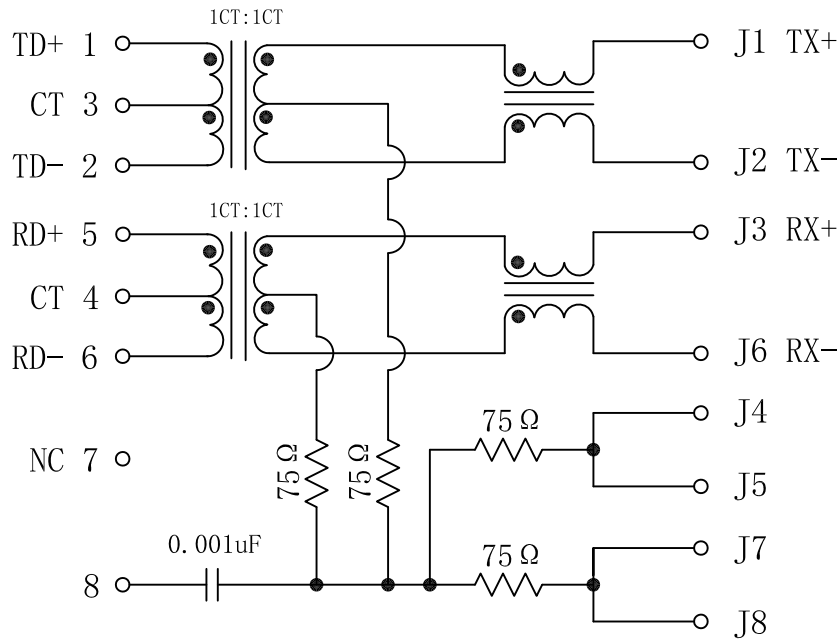


Schematic:

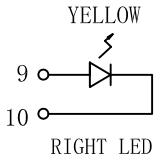
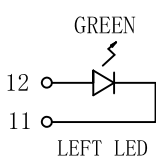
PCB SIDE TO PHY



CABLE

ELECTRICAL SPECIFICATIONS @25℃

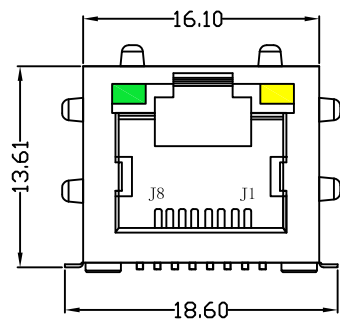
- Turn Ratio($\pm 3\%$):
TX=1CT:1CT RX=1CT:1CT
- Inductance OCL:
350uH MIN @ 100KHz 0.1V 8mA DC Bias
- DCR: 1.2 Ω MAX
- Insertion Loss:
-1.0dB MAX @ 1-100MHz
- Return Loss:
-18dB MIN @ 1-30MHz
-15dB MIN @ 30-60MHz
-12dB MIN @ 60-100MHz
- Cross talk:
-40dB MIN @ 1-30MHz
-35dB MIN @ 30-60MHz
-30dB MIN @ 60-100MHz
- Common Mode Rejection:
-30dB MIN @ 1-50MHz
-20dB MIN @ 50-100MHz
- Hipot Test: 1500Vrms
- Operating Temperature Range: 0℃ to 70℃.



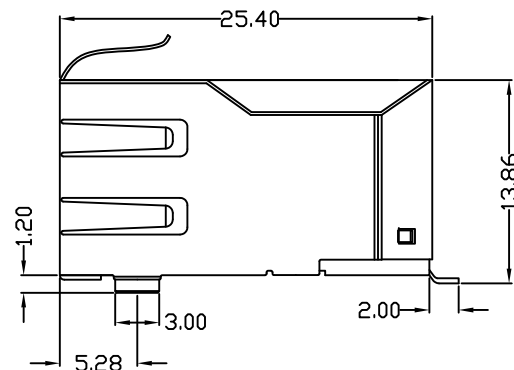
Emitting Color	λ p(nm)	VF@IF=20mA	IR @VR=5V
GREEN	565	1.8~2.4V	10 μ A max
YELLOW	585	1.8~2.4V	10 μ A max

X:X ± 0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX ± 0.25	CHKD:		
X:XXX ± 0.05	DR: TOM	TITLE: Surface Mount 1×1 Tab-Up Jack With 10/100M Magnetic	
ANGLES $\pm 1^\circ$	UNIT: mm	PART NO.: LPJ3011ABNL	
	SCALE: 2/1	SHEET: 2/2	REV: A DWG NO.: LP15051185

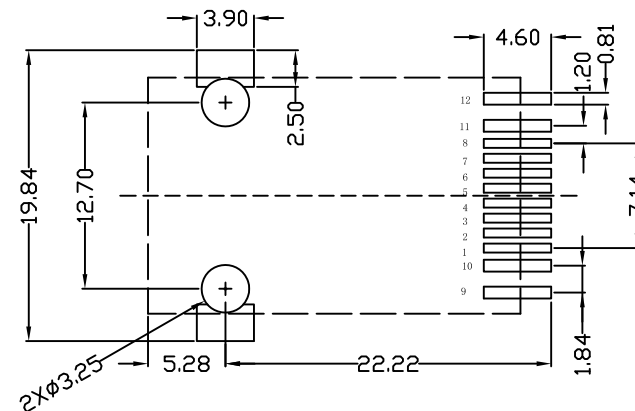
Mechanical:



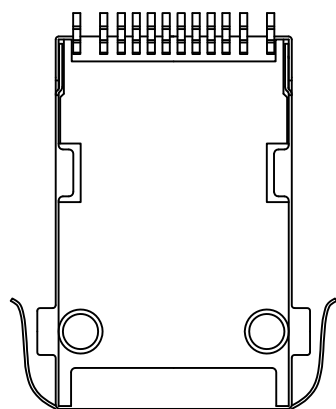
Front Side View



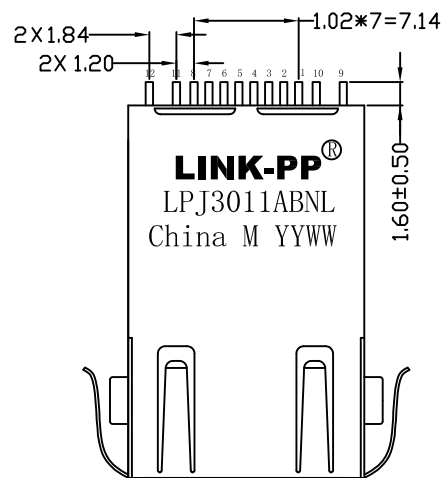
Left Side View



Suggested PCB Layout



Bottom Side View



Top Side View

NOTES:

1. Designed to support application, such as SOHO (ADSL modems), LAN-ON-Motherboard (LOM), hub and Swiches.
2. Meets IEEE 802.3 specification
3. Connector Materials:
Housing Material: Thermoplastic LCP+30%G.F UL94V-0
Contact Material: Phosphor Bronze C5210R-EH Thickness=0.35mm
Pins: Brass C2680R-H Thickness=0.35mm
Shield: SUS 201-1/2H Thickness=0.2mm
Contact plating: Gold 6 micro-inches min. In contact area.
4. Wave solder tip temperature: 265°C Max, 5 Sec.
5. UL Certification: File Number E484635.

X:X ±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED	
X:XX ±0.25	CHKD:		
X:XXX ±0.05	DR: TOM	TITLE: Surface Mount 1×1 Tab-Up Jack With 10/100M Magnetic	
ANGLES ±1°	UNIT: mm	PART NO.: LPJ3011ABNL	
	SCALE: 2/1	SHEET: 2/2	REV: A
		DWG NO.: LP15051185	